



SOT637

plastic single-ended multi-chip package; 6 interconnections;
5 in-line leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SIP5
Package type industry code	SIP5
Package style descriptive code	SIP (single in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	10-12-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21	-	21.2	21.4	mm
E	package width	5.25	-	5.35	5.45	mm
A ₂	package height	1.45	-	1.55	1.65	mm
n ₂	actual quantity of termination	-	-	5	-	



2. Package outline

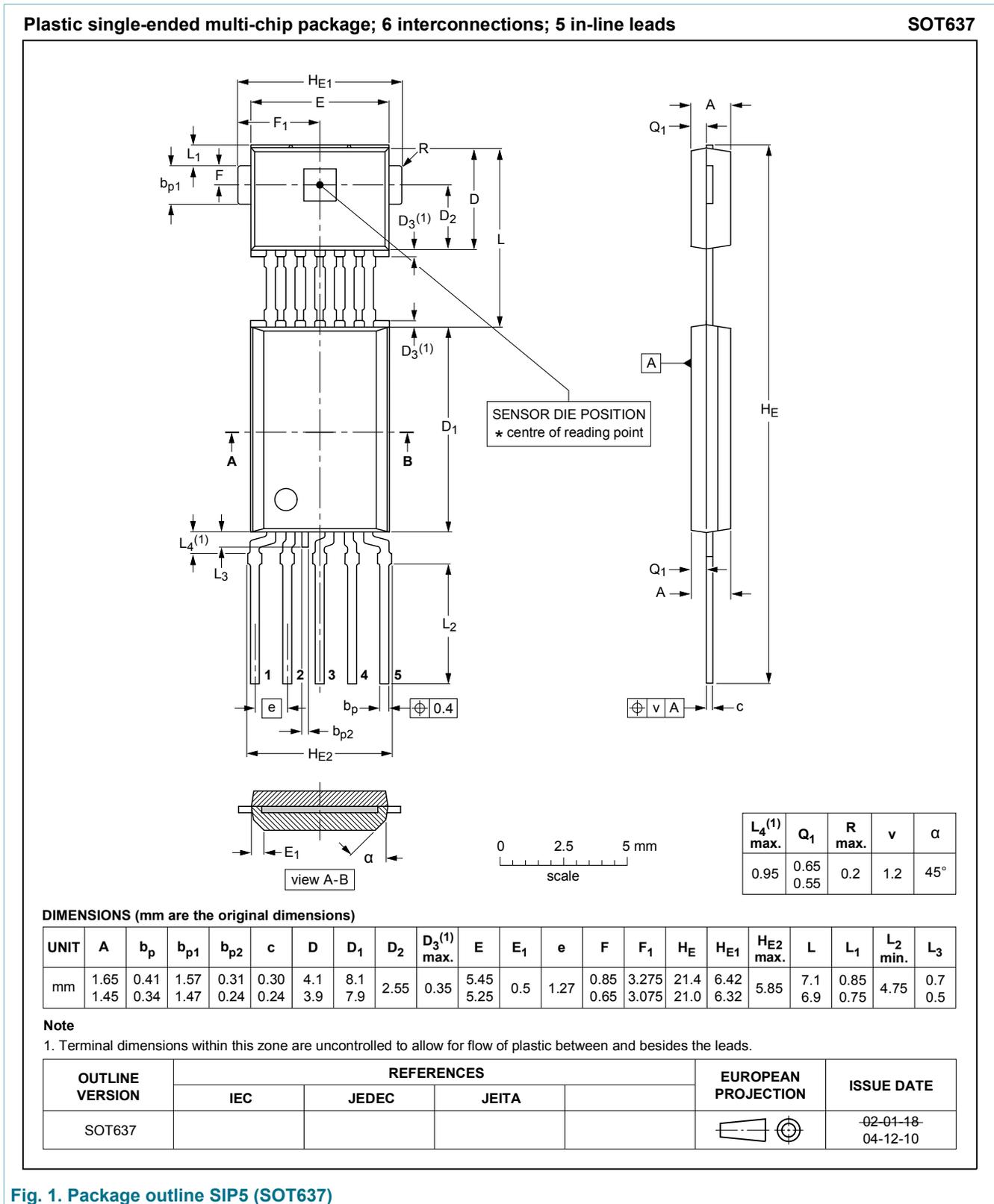


Fig. 1. Package outline SIP5 (SOT637)

3. Legal information

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